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SPECIFICATION



- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL31A106KACLNNC
- Descriptiont : CAP, 10µF, 25V, ±10%, X5R, 1206

A. Samsung Part Number

	<u>CL</u>	<u>31</u>	<u>A</u>	<u>106</u>	<u>K</u>	<u>A</u>	<u>C</u>	Ŀ	<u>N</u>	<u>N</u>	<u>C</u>	
	1	2	3	4	5	6	1	8	9	10	1	
Samsun	a Mult	i-lave	r Cer	amic (Cana	citor						

1	Series	Samsung Multi-layer Ceramic Capacitor								
2	Size	1206 (inch	code)	L: 3.2	± 0.2	mm	W:	1.6	± 0.2	mm
				(8)	Thickn	ess divisi	on	Low p	rofile	
3	Dielectric	X5R			Inner e	lectrode		Ni		
4	Capacitance	10 µF			Termin	ation		Cu		
5	Capacitance	±10 %			Plating	l		Sn 10	0%	(Pb Free)
	tolerance			9	Produc	ct		Norm	al	
6	Rated Voltage	25 V		10	Specia	I		Reser	ved for	future use
\bigcirc	Thickness	0.85 ± 0.1	mm	1	Packaging Cardboard T		ype,7"reel(4,000ea)			

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1kltz±10% 1.0±0.2Vrms					
Tan δ (DF)	0.1 max.						
Insulation	More than 100Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance							
Appearance	No abnormal exterior appearance	Visual inspection					
Withstanding	No dielectric breakdown or	250% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	X5R						
Characteristics	(From -55℃ to 85℃, Capacitance chang	ge should be within ±15%)					
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)					
		with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120 ℃ for 10~30sec.)					
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	Tan δ, IR : initial spec.						

	Performance	Test condition					
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm					
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)					
		2hours \times 3 direction (x, y, z)					
Moisture	Capacitance change : within ±12.5%	With rated voltage					
Resistance	Tan δ : 0.125 max	40±2℃, 90~95%RH, 500+12/-0 hour					
	IR ∶ More than 12.5MΩ· <i>μ</i> F						
High Temperature	Capacitance change : within ±12.5%	With 150% of the rated voltage					
Resistance	Tan δ : 0.125 max	Max. operating temperature					
	IR : More than 25MΩ· <i>μ</i> F						
		1000+48/-0 hour					
Temperature	Capacitance change : within ±7.5%	1 cycle condition					
Cycling	Tan δ, IR : initial spec.	Min. operating temperature \rightarrow 25 °C					
		\rightarrow Max. operating temperature \rightarrow 25 °C					
		5 cycles test					

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.